

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Serial No. ....10/825,839  
Filing Date ..... April 15, 2004  
Confirmation No. .... 9446  
Inventor ..... Lee Teck Kheng  
Assignee ..... Micron Technology, Inc  
Group Art Unit ..... 2814  
Examiner ..... Abul Kalam  
Attorney's Docket No. .... MI22-2460  
Title:..... Semiconductor Packages comprising Interposer Constructions

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**


References - - See attached Form PTO/SB/08A-B

The attached Form PTO/SB/08 is submitted in compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, and your attention is directed to the references listed on the attached Form PTO/SB/08. No admission is made regarding whether the submitted references are prior art.

Citation of these references is respectfully requested.

Respectfully submitted,

Dated: 10-27-08

By:   
D. Brent Kenady  
Reg. No. 40045